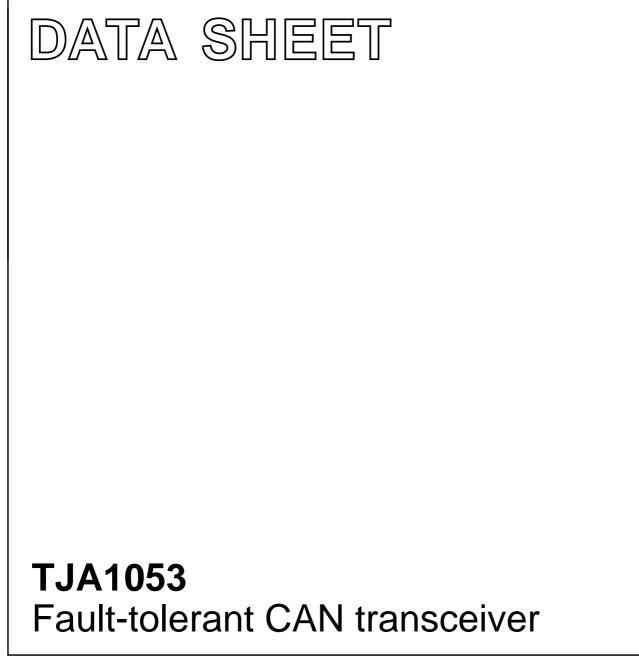
## INTEGRATED CIRCUITS



Preliminary specification File under Integrated Circuits, IC18 1997 Oct 15



HILIP

## TJA1053

### FEATURES

### Optimized for in-car low-speed communication

- Baud rate up to 125 kbaud
- Up to 32 nodes can be connected
- Supports unshielded bus wires
- Low RFI due to built-in slope control function
- Fully integrated receiver filters
- Permanent dominant monitoring of TXD.

### Bus failure management

- Supports one-wire transmission modes with ground offset voltages up to 1.5 V
- Automatic switching to single-wire mode in the event of bus failure
- Automatic reset to differential mode if bus failure is removed.

### Protection

- Short-circuit proof to battery and ground in 12 V powered systems
- Thermally protected
- Bus lines protected against transients in an automotive environment
- An unpowered node does not disturb the bus lines.

#### Support for low-power modes

- Low current sleep/standby mode with wake-up via the bus lines
- Power-on reset flag on the output.

### **GENERAL DESCRIPTION**

The TJA1053 is the interface between the CAN protocol controller and the physical bus. It is primarily intended for low-speed applications, up to 125 kbaud, in passenger cars. The device provides differential transmit capability but will switch in error conditions to a single-wire transmitter and/or receiver. The TJA1053 is derived from the PCA82C252.

- 1. It is better equipped for networks with more than 15 nodes
- 2. A timer has been integrated at the TXD input to prevent a permanent dominant state
- 3. Reduced supply current in  $V_{CC}$  standby mode
- 4. CANH output driver is disabled in the event that CANH is short-circuited to battery failure mode.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MIN.	UNIT
V <sub>CC</sub>	supply voltage		4.75	_	5.25	V
V <sub>BAT</sub>	battery voltage	no time limit	-0.3	-	+27	V
		operating	6.0	-	27	V
		load dump	-	-	40	V
I <sub>sleep</sub>	sleep mode current	V <sub>CC</sub> = 0 V; V <sub>BAT</sub> = 12 V	-	65	-	μA
V <sub>CANH</sub> ,V <sub>CANL</sub>	CANH, CANL input voltage	$\label{eq:V_CC} \begin{array}{l} V_{CC} = 0 \text{ to } 5.5 \text{ V}; \ V_{BAT} \geq 0 \text{ V}; \\ \text{no time limit} \end{array}$	-10	-	+27	V
		$\label{eq:V_CC} \begin{array}{l} V_{CC} = 0 \text{ to } 5.5 \text{ V}; \ V_{BAT} \geq 0 \text{ V}; \\ t < 0.1 \text{ ms; load dump} \end{array}$	-40	-	+40	V
V <sub>DROP(H)</sub>	CANH transmitter drop voltage	I <sub>CANH</sub> = 40 mA	-	-	1.4	V
V <sub>DROP(L)</sub>	CANL transmitter drop voltage	I <sub>CANL</sub> = 40 mA	-	-	1.4	V
t <sub>PD</sub>	propagation delay	TXD to RXD	-	1	-	μs
t <sub>f</sub>	bus output fall time	90% to 10%	-	0.5	-	μs
t <sub>r</sub>	bus output rise time	10% to 90%	-	0.5	-	μs
T <sub>amb</sub>	operating ambient temperature		-40	_	+125	°C

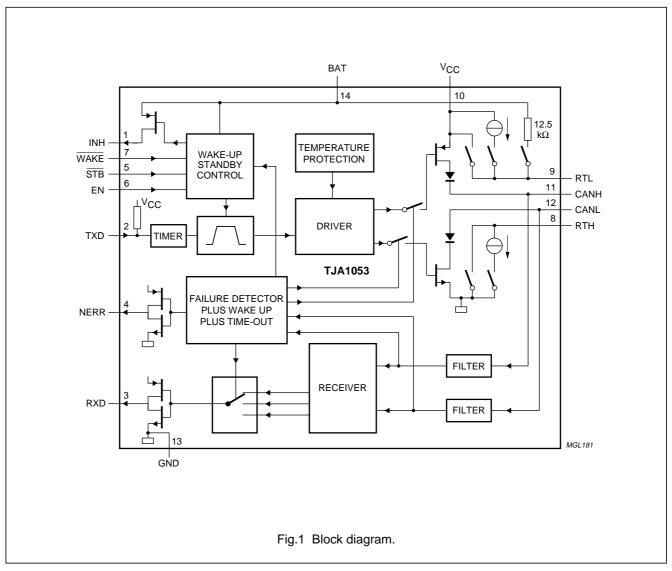
### QUICK REFERENCE DATA

### TJA1053

#### ORDERING INFORMATION

TYPE	PACKAGE				
NUMBER	NAME	NAME DESCRIPTION			
TJA1053T	SO14	plastic small outline package; 14 leads; body width 3.9 mm SOT			

### **BLOCK DIAGRAM**



## TJA1053

### PINNING

SYMBOL	PIN	DESCRIPTION
INH	1	inhibit output for switching external 5 V regulator
TXD	2	transmit data input, when LOW bus data will be dominant, when HIGH bus data will be recessive
RXD	3	receive data output, when LOW bus data will be dominant
NERR	4	error output pin, when LOW a bus error exists
STB	5	not standby digital control input signal (active LOW)
EN	6	enable digital control input signal
WAKE	7	not wake input signal, when pulled down INH becomes active for wake-up (active LOW)
RTH	8	termination resistor, CANH line will be high-impedance with certain bus errors
RTL	9	termination resistor, CANL line will be high-impedance with certain bus errors
V <sub>CC</sub>	10	supply voltage (+5 V)
CANH	11	high voltage bus line, will be HIGH in dominant state
CANL	12	low voltage bus line, will be LOW in dominant state
GND	13	ground
BAT	14	battery voltage

### TJA1053

### FUNCTIONAL DESCRIPTION

The TJA1053 is the interface between the CAN protocol controller and the physical bus. It is primarily intended for low speed applications, up to 125 kBaud, in passenger cars. The device provides differential transmit capability to the bus and differential receive capability to the CAN controller.

To reduce RF interference the rise and fall slope are limited. This allows the use of an unshielded twisted pair or a parallel pair of wires for the bus. Moreover, it supports transmission capability on either bus wire if one of the bus wires is corrupted. The failure detection logic automatically selects a suitable transmission mode.

In normal operation (no wiring failures) the differential receiver is output to RXD. The differential receiver inputs are connected to CANH and CANL through integrated filters. The filtered input signals are also used for the single wire receivers. The CANH and CANL receivers have threshold voltages that ensure a maximum noise margin in single-wire modes.

A timer has been integrated at the TXD input. This timer prevents the TJA1053 to drive the bus lines to permanent dominant state.

#### Failure detector

The failure detector is active in the normal operation mode and detects the following single bus failures and switches to an appropriate mode:

- 1. CANH wire interrupted
- 2. CANL wire interrupted
- 3. CANH short-circuited to battery
- 4. CANL short-circuited to ground
- 5. CANH short-circuited to ground
- 6. CANL short-circuited to battery
- 7. CANL mutually shorted to CANH.

The differential receiver threshold is set at -2.9 V. This ensures correct reception in the normal operating modes and, in the event of failures 1, 2 and 5 with a noise margin as high as possible. These failures, or recovery from them, do not destroy ongoing transmissions.

Failures 3 and 6 are detected by comparators connected to CANH and CANL, respectively. If the comparator threshold is exceeded for a certain period of time, the reception is switched to the single-wire mode. This time is needed to avoid false triggering by external RF fields. Recovery from these failures is detected automatically after a certain time-out (filtering) and no transmission is lost. The CANH driver and the RTH pin are switched off in the event of failure 3.

Failures 4 and 7 initially result in a permanent dominant level at RXD. After a time-out, the CANL driver and the RTL pin are switched off. Only a weak pull-up at RTL remains. Reception continues by switching to the single-wire mode via CANH. When failures 4 or 7 are removed, the recessive bus levels are restored. If the differential voltage remains below the recessive threshold level for a certain period of time, reception and transmission switch back to the differential mode.

If any of the seven wiring failures occur, the output NERR will be made LOW. On error recovery, NERR will be made HIGH again.

During all single-wire transmissions, the EMC performance (both immunity and emission) is worse than in the differential mode. Integrated receiver filters suppress any HF noise induced into the bus wires. The cut-off frequency of these filters is a compromise between propagation delay and HF suppression. In the single-wire mode, low frequency noise cannot be distinguished from the required signal.

#### Low power modes

The transceiver provides 3 low power modes which can be entered and exited via pins STB and EN (see Table 1).

The sleep mode is the mode with the lowest power consumption. The INH pin is switched to high-impedance for deactivation of external voltage regulators. CANL is biased to the battery voltage via the RTL output. If the supply voltage is provided the RXD and NERR will signal the wake-up interrupt

The  $V_{\text{BAT}}$  standby mode will react the same as the sleep mode with an active INH output.

The V<sub>CC</sub> standby mode is the V<sub>BAT</sub> standby with RTL switched to the V<sub>CC</sub> voltage. In this mode the NERR output signals the V<sub>BAT</sub> power-on flag and the RXD output will show the wake-up interrupt.

### TJA1053

Wake-up requests are recognized by the transceiver when a dominant signal is detected on either bus line or if the WAKE pin is connected to ground. On a wake-up request the transceiver will set the INH output which can be used to activate the external  $V_{CC}$  voltage regulator. If  $V_{CC}$  is provided the wake-up request can be read on the NERR or RXD outputs, on which the external microcontroller can wake up the transceiver (switch to normal operating mode) via STB and EN.

To prevent false wake-up due to transients or RF fields, wake-up voltage threshold levels have to be maintained for a certain period of time. In the low power modes the failure detection circuit remains partly active to prevent increased power consumption should errors 3, 4 and 7 occur.

### Power on

After power-on  $V_{BAT}$  is switched on, the INH pin will become HIGH and an internal power-on flag will be set. This flag can be read via the NERR pin (STB = 1, EN = 0) and will be reset by entering the normal operation mode. The EN and  $\overline{\text{STB}}$  pins will internally be set to LOW level, if the V<sub>CC</sub> voltage is below a certain threshold level, to provide fail safe functionality.

### Protections

A current limiting circuit protects the transmitter output stages against short-circuit to positive and negative battery voltage.

If the junction temperature exceeds a maximum value, the transmitter output stages are disabled. Because the transmitter is responsible for the major part of the power dissipation, this will result in a reduced power dissipation and hence a lower chip temperature. All other parts of the IC will remain operating.

The CANH and CANL inputs are protected against electrical transients which may occur in an automotive environment.

STB	EN	MODE	INH	NERR RXD		RTL
0	0	V <sub>BAT</sub> standby <sup>(1)</sup>	HIGH	active LOW wake-up interr	rupt signal if V <sub>CC</sub> is present	switched to $V_{\text{BAT}}$
0	0	sleep <sup>(2)</sup>	floating			switched to $V_{\text{BAT}}$
0	1	go to sleep command	floating			switched to $V_{\text{BAT}}$
1	0	V <sub>CC</sub> standby <sup>(3)</sup>	HIGH	active LOW V <sub>BAT</sub> power-on flag	active LOW wake-up interrupt	switched to $V_{\mbox{CC}}$
1	1	normal operation mode	HIGH	active LOW error flag	HIGH = receive; LOW = dominant received data	switched to $V_{CC}$

### Table 1 Truth table of CAN transceiver

#### Notes

- 1. Wake-up interrupts are released when entering normal operating mode.
- If go to sleep command was used before (EN may turn LOW as V<sub>CC</sub> drops, without affecting internal functions because of fail safe functionality).
- 3.  $V_{BAT}$  power-on flag will be reset when entering normal operation mode.

### TJA1053

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CC</sub>	supply voltage		-0.3	+6.0	V
V <sub>DD</sub>	DC input voltage at pins 2 to 6		-0.3	V <sub>CC</sub> + 0.3	V
V <sub>BUS</sub>	DC input voltage at pins 11 and 12		-10	+27	V
V <sub>CANH,L</sub>	DC input voltage at pins 11 and 12	$\label{eq:V_CC} \begin{array}{l} V_{CC} = 0 \text{ to } 5.5 \text{ V}; \\ V_{BAT} \geq 0 \text{ V}; t < 0.1 \text{ ms}; \\ \text{load dump} \end{array}$	-40	+40	V
V <sub>tr</sub>	transient voltage at pins 11 and 12	see Fig.6	-150	+100	V
V <sub>WAKE</sub>	DC input voltage on pin 7		-	V <sub>BAT</sub> + 0.3	V
I <sub>WAKE</sub>	input current pin 7		-15	-	mA
V <sub>1,8,9</sub>	DC input voltage on pins 1, 8 and 9		-0.3	V <sub>BAT</sub> + 0.3	V
V <sub>BAT</sub>	DC input voltage on pin 14		-0.3	+27	V
	voltage on pin 14	load dump; 500 ms	-	40	V
R <sub>8,9</sub>	termination resistances pins 8 and 9		500	16000	Ω
T <sub>vj</sub>	virtual junction temperature	note 1	-40	+150	°C
T <sub>stg</sub>	storage temperature		-55	+150	°C
V <sub>esd</sub>	electrostatic discharge voltage at any pin	note 2	-2000	+2000	V
		note 3	-200	+200	V

#### Notes

 Junction temperature in accordance with IEC 747-1. An alternative definition is: T<sub>vj</sub> = T<sub>amb</sub> + PD × R<sub>th vj-a</sub>. Where: R<sub>th vj-a</sub> is a fixed value to be used for the calculation of T<sub>vj</sub>. The rating for T<sub>vj</sub> limits the allowable combinations of power dissipation and ambient temperature.

- 2. Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 k $\Omega$  resistor.
- 3. Machine model: equivalent to discharging a 200 pF capacitor through a 25  $\Omega$  resistor.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th vj-a</sub>	thermal resistance from junction to ambient	in free air	120	K/W

#### QUALITY SPECIFICATION

Quality specification in accordance with "SNW-FQ-611-Part-E".

TJA1053

### CHARACTERISTICS

 $V_{CC}$  = 4.75 to 5.25 V;  $V_{\overline{STB}}$  =  $V_{CC}$ ;  $V_{BAT}$  = 6 to 27 V;  $T_{amb}$  = -40 to +125 °C; unless otherwise specified. All voltages are defined with respect to ground. Positive currents flow into the IC. All parameters are guaranteed over the temperature range by design, but only 100% tested at 25 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies					ļ	
I <sub>CC</sub>	supply current	recessive; TXD = V <sub>CC</sub> ; normal operating mode	-	6	10	mA
		dominant; TXD = 0 V; no load; normal operating mode	-	29	35	mA
I <sub>CC</sub> + I <sub>BAT</sub>	supply current	$V_{CC}$ standby; $V_{CC}$ = 5 V; $V_{BAT}$ = 12 V; $T_{amb}$ < 90 °C	_	200	500	μA
I <sub>BAT</sub> + I <sub>CC</sub>	supply current	$V_{BAT}$ standby; $V_{CC}$ = 5 V; $V_{BAT}$ = 12 V; $T_{amb}$ < 90 °C	_	70	95	μA
I <sub>BAT</sub>	supply current	sleep mode; $V_{CC} = 0 V$ ; $V_{BAT} = 12 V$ ; $T_{amb} < 90 °C$	-	65	90	μA
V <sub>BAT</sub>	battery voltage for setting power-on flag	low power modes	_	-	1.0	V
t <sub>pwon</sub>	battery voltage low time for setting power-on flag	low power modes	1	-	_	S
Pins STB,	EN and TXD					
V <sub>IH</sub>	HIGH-level input voltage		0.7V <sub>CC</sub>	-	V <sub>CC</sub> + 0.3	V
V <sub>IL</sub>	LOW-level input voltage		-0.3	-	0.3V <sub>CC</sub>	V
I <sub>IH</sub>	HIGH-level input current (pins STB and EN)	$V_i = 4 V$	-	9	20	μA
IIL	LOW-level input current (pins STB and EN)	V <sub>i</sub> = 1 V	4	8	-	μA
I <sub>IH</sub>	HIGH-level input current (pin TXD)	$V_i = 4 V$	-25	-80	-200	μA
IIL	LOW-level input current (pin TXD)	V <sub>i</sub> = 1 V	-100	-320	-800	μA
V <sub>CC</sub>	forced V <sub>BAT</sub> standby mode (fail safe)		2.75	-	4.5	V
Pins RXD	and NERR				·	
V <sub>OH</sub>	HIGH-level output voltage (pin NERR)	I <sub>o</sub> = -100 μA	V <sub>CC</sub> – 0.9	-	V <sub>CC</sub>	V
V <sub>OH</sub>	HIGH-level output voltage (pin RXD)	I <sub>o</sub> = -250 μA	V <sub>CC</sub> – 0.9	-	V <sub>CC</sub>	V
V <sub>OL</sub>	LOW-level output voltage	l <sub>o</sub> = 1.25 mA	0	_	0.9	V
Pin WAKE						
IIL	LOW-level input current	$V_{\overline{WAKE}} = 0 V; V_{BAT} = 27 V$	-70	-40	-10	μA
V <sub>wu(th)</sub>	wake-up threshold voltage	$V_{\overline{STB}} = 0 V$	1.7	3.0	4.0	V

## TJA1053

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Pin INH	I		1		1	
V <sub>dropH</sub>	HIGH-level voltage drop	I <sub>INH</sub> = -0.18 mA; V <sub>BAT</sub> < 16 V	_	_	0.8	V
·		I <sub>INH</sub> = -0.18 mA; V <sub>BAT</sub> > 16 V	-	-	1.0	V
ILI	leakage current	sleep mode; V <sub>INH</sub> = 0 V	-5.0	-	+5.0	μA
Pins CANH	and CANL					
V <sub>drx</sub>	differential receiver threshold voltage	no bus failures bus failures 1, 2 and 5	-3.25	-	-2.65	V
V <sub>oCANHrec</sub>	CANH recessive output voltage	TXD = $V_{CC}$ ; $R_{RTH} < 4 \text{ k}\Omega$	_	-	0.2	V
V <sub>oCANLrec</sub>	CANL recessive output voltage	TXD = $V_{CC}$ ; $R_{RTL} < 4 \text{ k}\Omega$	V <sub>CC</sub> – 0.2	-	-	V
V <sub>oCANHdom</sub>	CANH dominant output voltage	$TXD = 0 V; V_6 = V_{CC};$ $I_{CANH} = -40 mA$	V <sub>CC</sub> – 1.4	-	-	V
V <sub>oCANLdom</sub>	CANL dominant output voltage	$TXD = 0 V; V_6 = V_{CC};$ I <sub>CANL</sub> = 40 mA	_	-	1.4	V
I <sub>oCANH</sub>	CANH output current	V <sub>CANH</sub> = 0 V; TXD = 0 V	_	-75	-100	mA
		sleep mode; V <sub>CANH</sub> = 12 V	-	0	-	μA
I <sub>oCANL</sub>	CANL output current	V <sub>CANL</sub> = 14 V; TXD = 0 V	-	90	130	mA
		sleep mode; $V_{CANL} = 0 V$ ; $V_{BAT} = 12 V$	-	0	-	μA
V <sub>det(th)H,L</sub>	voltage detection threshold for short-circuit to battery voltage on CANH and CANL	normal mode	6.5	7.3	8.0	V
V <sub>det(th)H</sub>	voltage detection threshold for short-circuit to battery voltage on CANH	standby/sleep mode	V <sub>BAT</sub> – 2.5	-	V <sub>BAT</sub> – 1	V
V <sub>wuL</sub>	CANL wake-up voltage threshold		2.4	3.1	3.8	V
V <sub>wuH</sub>	CANH wake-up voltage threshold		1.2	1.9	2.7	V
V <sub>wuL</sub> -V <sub>wuH</sub>	wake-up voltage threshold difference		0.2	-	-	V
V <sub>CANH</sub>	CANH single-ended receiver threshold	failures 4, 6 and 7	1.5	1.82	2.15	V
V <sub>CANL</sub>	CANL single-ended receiver threshold voltage	failure 3	2.8	3.1	3.4	V

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Pins RTH a	and RTL		•		1	
R <sub>RTL</sub>	RTL to $V_{CC}$ switch-on resistance	I₀I < 10 mA; normal operating mode	-	7	25	Ω
		I₀  < 1 mA; V <sub>CC</sub> standby mode	-	15	75	Ω
	RTL to V <sub>BAT</sub> switch series resistance	V <sub>BAT</sub> standby or sleep mode	8	12.5	23	kΩ
R <sub>RTH</sub>	RTH to ground switch-on resistance	I₀I < 10 mA; normal operating mode	-	43	95	Ω
V <sub>oRTH</sub>	RTH output voltage	I <sub>o</sub> = 1 mA; low power modes	_	0.7	1.0	V
I <sub>RTLpu</sub>	RTL pull-up current	normal operating mode, failures 4, 6 and 7	-	75	_	μA
I <sub>RTHpd</sub>	RTH pull-down current	normal operating mode, failure 3	-	75	-	μA
Thermal sl	nutdown	•	•			•
T <sub>jsd</sub>	shutdown junction temperature		155	165	180	°C

### AC CHARACTERISTICS

 $V_{CC}$  = 4.75 to 5.25 V;  $V_{\overline{STB}}$  =  $V_{CC}$ ;  $V_{BAT}$  = 6 to 27 V;  $T_{amb}$  = -40 to +125 °C; unless otherwise specified. All voltages are defined with respect to ground. Positive currents flow into the IC. All parameters are guaranteed over the temperature range by design, but only 100% tested at 25 °C.

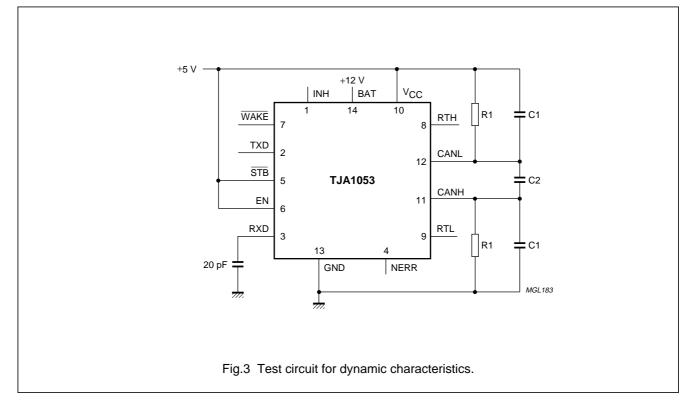
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t <sub>t(r-d)</sub>	CANL and CANH bus output transition time recessive-to-dominant	10% to 90%; C1 = 10 nF; C2 = 0; R1 = 100 $\Omega$	0.6	0.85	-	μs
t <sub>t(d-r)</sub>	CANL and CANH bus output transition time dominant-to-recessive	10% to 90%; C1 = 1 nF; C2 = 0; R1 = 100 $\Omega$	0.3	0.4	-	μs
t <sub>PD(L)</sub>	propagation delay TXD-to-RXD LOW	C1 = 100 pF; C2 = 0; R1 = 100 $\Omega$ ; no failures and bus failures 1, 2 and 5	-	0.75	1.25	μs
		C1 = C2 = 3.3 nF; R1 = 100 $\Omega$ ; no failures and bus failures 1, 2 and 5	_	1	1.5	μs
		C1 = 100 pF; C2 = 0; R1 = 100 $\Omega$ ; bus failures 3, 4, 6 and 7	-	0.85	1.3	μs
		C1 = C2 = 3.3 nF; R1 = 100 $\Omega$ ; bus failures 3, 4, 6 and 7	-	1.1	1.7	μs

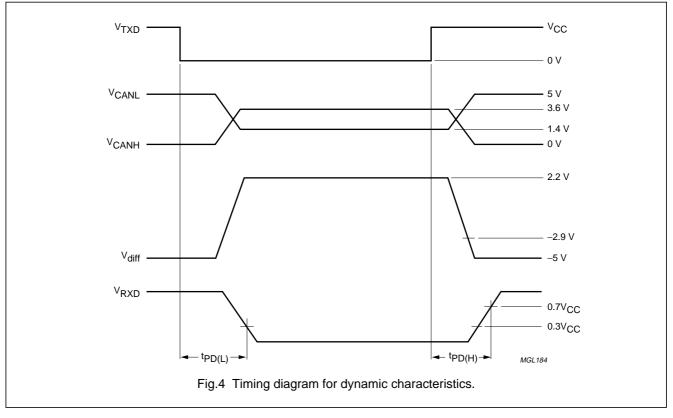
## TJA1053

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t <sub>PD(H)</sub>	propagation delay TXD-to-RXD HIGH	C1 = 100 pF; C2 = 0; R1 = 100 $\Omega$ ; no failures and bus failures 1, 2 and 5	_	0.95	1.5	μs
		C1 = C2 = 3.3 nF; R <sub>I</sub> = 100 $\Omega$ ; no failures and bus failures 1 and 2	-	2.2	3.0	μs
		C1 = 100 pF; C2 = 0; R1 = 100 $\Omega$ ; bus failures 3, 4, 6 and 7	-	0.85	1.3	μs
		C1 = C2 = 3.3 nF; R1 = 100 $\Omega$ ; bus failures 3, 4, 5, 6 and 7	-	1.4	2.1	μs
t <sub>wu(min)</sub>	minimum dominant time for wake-up on CANL or CANH	low power modes V <sub>BAT</sub> = 12 V	8	-	38	μs
t <del>WAKE</del> (min)	minimum WAKE LOW time for wake-up	low power modes V <sub>BAT</sub> = 12 V	8	-	38	μs
t <sub>fail</sub>	failure 3 detection time	normal mode	10	_	60	μs
	failure 6 detection time	normal mode	50	_	400	μs
	failure 3 recovery time	normal mode	10	_	60	μs
	failure 6 recovery time	normal mode	150	-	750	μs
	failures 4 and 7 detection time	normal mode	0.75	-	4.0	ms
	failures 4 and 7 recovery time	normal mode	10	-	60	μs
	failures 3, 4 and 7 detection time	low power modes; V <sub>BAT</sub> = 12 V	0.8	-	8.0	ms
	failures 3, 4 and 7 recovery time	low power modes; V <sub>BAT</sub> = 12 V	-	4	-	ms
t <sub>TXD</sub>	TXD permanent dominant timer, disable time	normal mode and failure modes	0.75	-	4.0	ms
t <sub>h(min)</sub>	minimum hold time to go to sleep command		5	-	50	μs
Δec	edge-count difference between CANH and CANL					
	for failures 1, 2 and 5 detection (NERR becomes LOW)	normal mode	-	3	_	
	for failures 1, 2 and 5 recovery	normal mode	_	1	_	

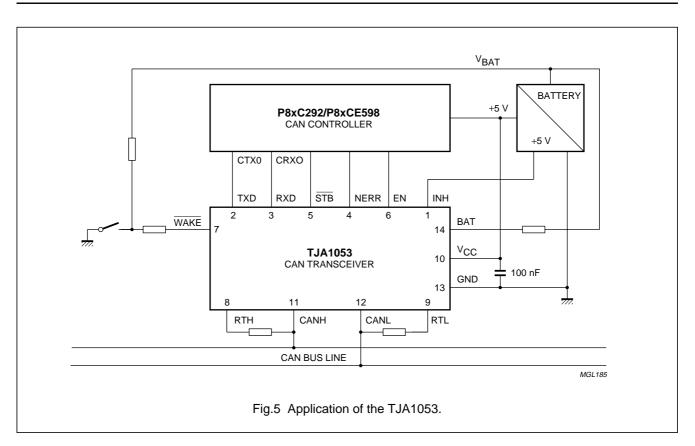
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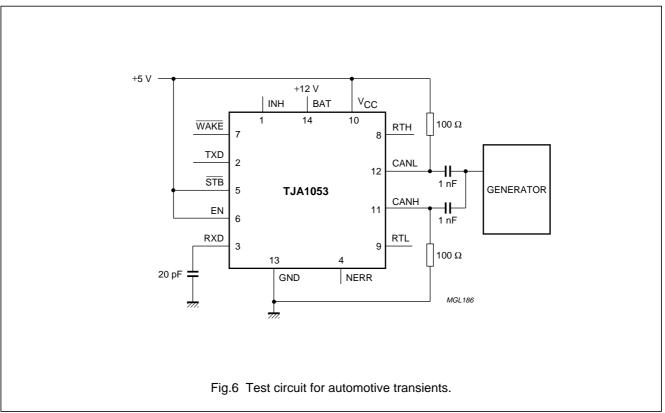
### **TEST AND APPLICATION INFORMATION**





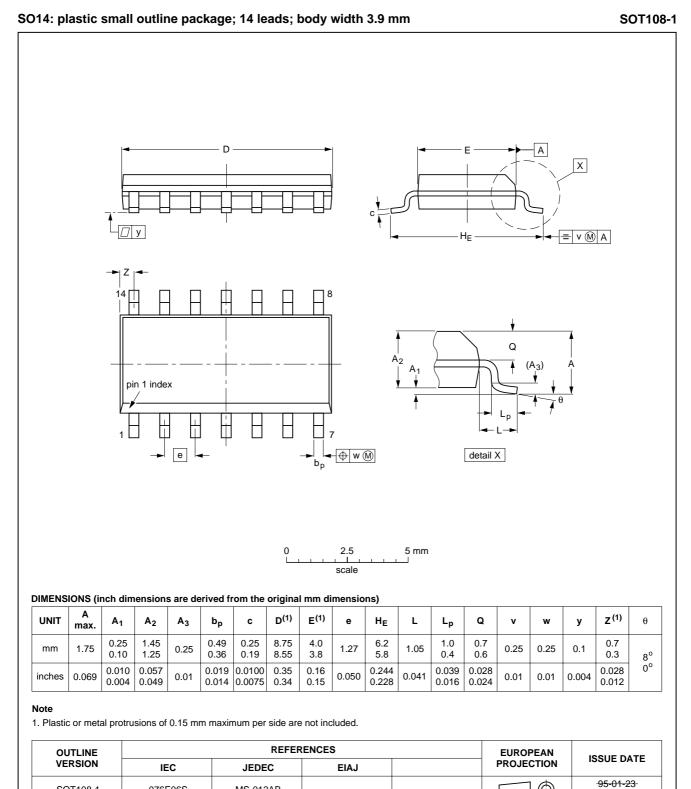
## TJA1053





### **TJA1053**

### PACKAGE OUTLINE



SOT108-1

076E06S

MS-012AB

 $\square$ 

97-05-22

### TJA1053

### SOLDERING

### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

### **Reflow soldering**

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to  $250 \,^{\circ}$ C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

### Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### **Repairing soldered joints**

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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### DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
more of the limiting values r of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.				
Application information					

Where application information is given, it is advisory and does not form part of the specification.

### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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Printed in The Netherlands

897027/00/01/pp20

Date of release: 1997 Oct 15

Document order number: 9397 750 02465

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